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TITLE: SEMICONDUCTOR DEVICE AND METHOD OF MANUFACTURING THE SAME

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ABSTRACT:

PROBLEM TO BE SOLVED: To realize a semiconductor device which can be automated in its subsequent steps by applying an identification symbol to a chip itself to provide mechanical identification by the symbol.

SOLUTION: An identification code 4 is provided at a predetermined position of a semiconductor chip 1, and the chip 1 is sealed in a package so that the identification code 4 can be externally read out from outside of the package 2.

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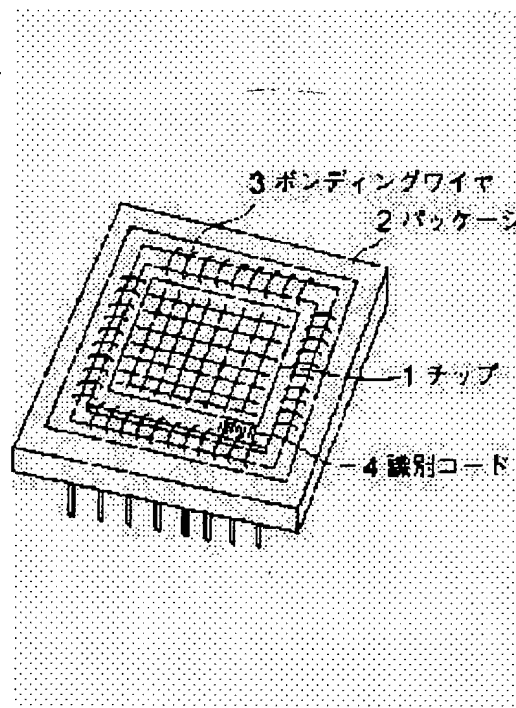
KIJOKA TOMOYASU

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